CRMGGH0604AD

Dual N-Channel 60V, 5.2mΩ Typ. Power MOSFET

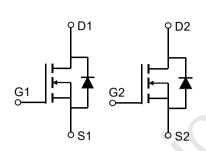
Description

Features

• 60V, 65A

$$R_{DS(ON)}$$
 Typ = 5.2m Ω @ V_{GS} = 10 V

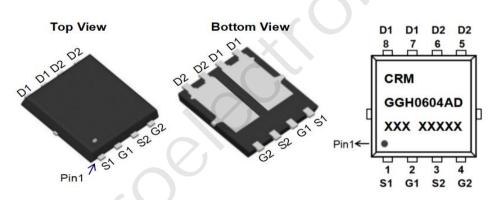
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH0604AD	CRMGGH0604AD	PDFN5x6-8L-D	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	65	А
I _D		T _C = 100°C	39	А
I _{DM}	Pulsed Drain Current ⁽¹⁾		260	А
E _{AS}	Single Pulsed Avalanche Energy (2)		121	mJ
P_{D}	Power Dissipation	T _C = 25°C	51	W
$R_{ hetaJC}$	Thermal Resistance, Junction to Case		2.45	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C



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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
	acteristics			,,		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60V, V _{GS} = 0V	-	-	1.0	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				G	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	2.8	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 20A	-	5.2	6.8	mΩ
	Characteristics					
C _{iss}	Input Capacitance		- /	1563	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 30V,$ f = 1MHz	-	580	-	pF
C_{rss}	Reverse Transfer Capacitance	I – TIVINZ	X - \	14	-	pF
Q_g	Total Gate Charge		-	29	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 30V, I_{D} = 20A$	<u> </u>	8.3	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 30 V, I _D - 20A	-	5.8	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	10	-	ns
t_r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 30V$	-	28	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 20A, R_{GEN} = 4.5\Omega$	-	20	-	ns
t_f	Turn-Off Fall Time		-	95	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	65	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	260	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 20 A - 4:1/4" - 4.00 A /	-	31	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20A$, di/dt = 100A/us	-	19	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =15V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =22A

^{3.} Pulse Test: Pulse Width $\!\!\leqslant\! 300\mu s,$ Duty Cycle $\!\!\leqslant\! 0.5\%.$

Test Circuit

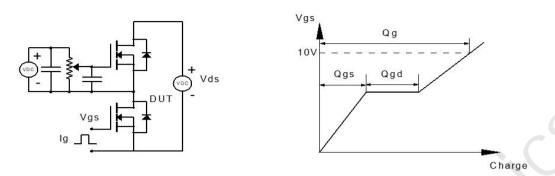


Figure 1: Gate Charge Test Circuit & Waveform

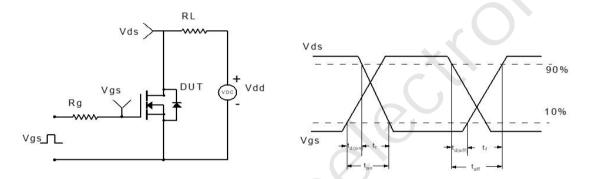


Figure 2: Resistive Switching Test Circuit & Waveform

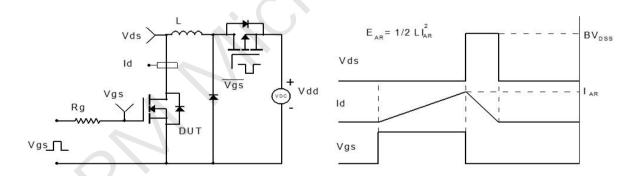


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

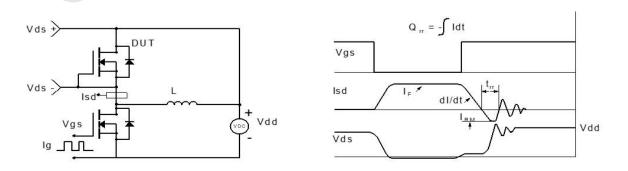
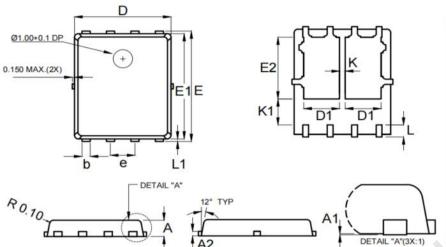


Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(PDFN5x6-8L-D)



Dimensio	ons In M	lillimeter	r	
Symbol	MIN	TYP	MAX	
Α	0.90	1.00	1.10	
A1	0.00	0.03	0.05	
A2	0.254 REF			
b	0.25	0.30	0.35	
D	4.80	4.90	5.00	
D1	1.60	1.70	1.80	
E	5.90	6.00	6.10	
E1	5.65	5.75	5.85	
E2	3.38	3.48	3.58	
е	1.27 BSC			
K	0.55	0.60	0.65	
K1	1.35 REF			
E	0.55	0.60	0.65	
L1	0.10	0.13	0.16	

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